



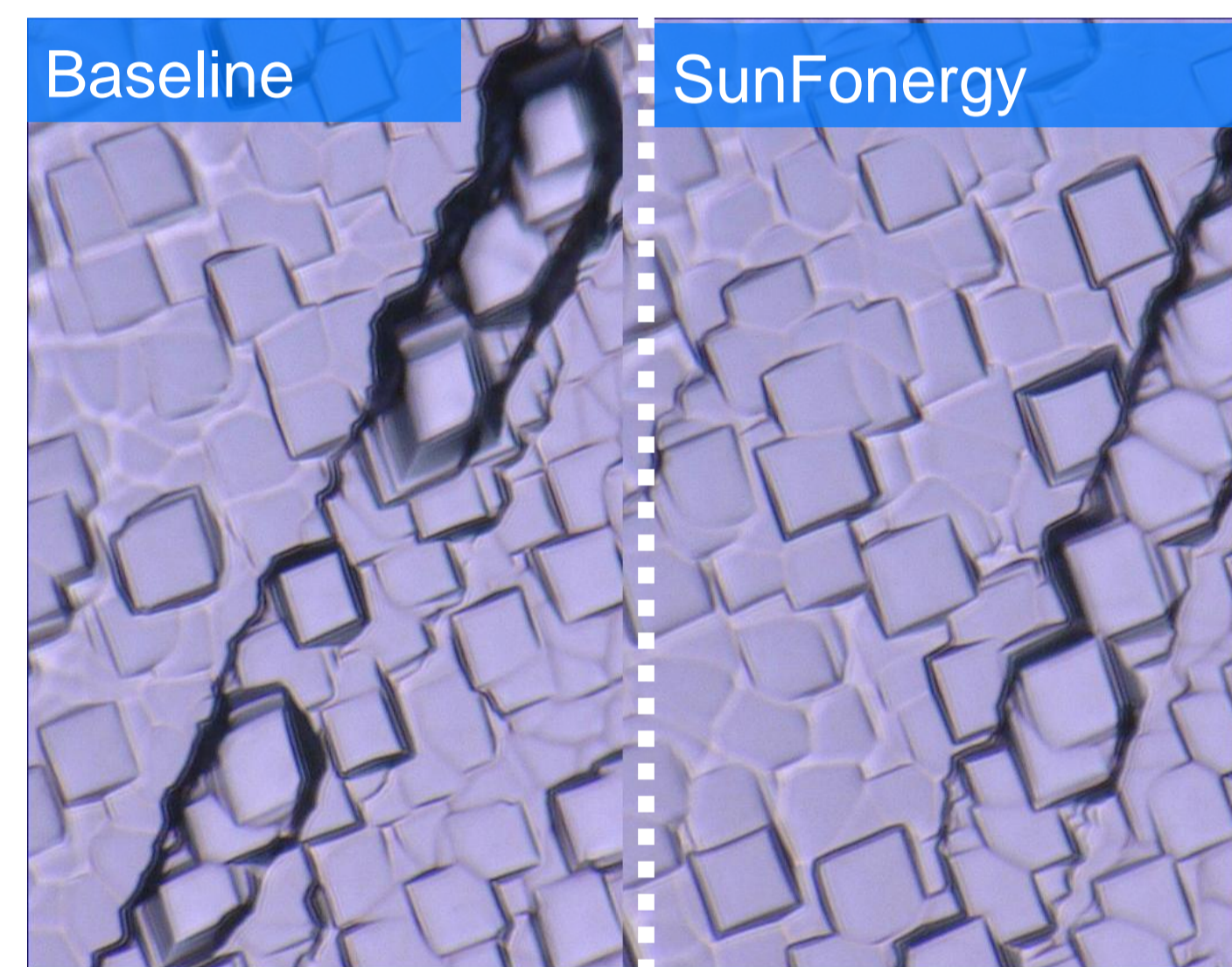
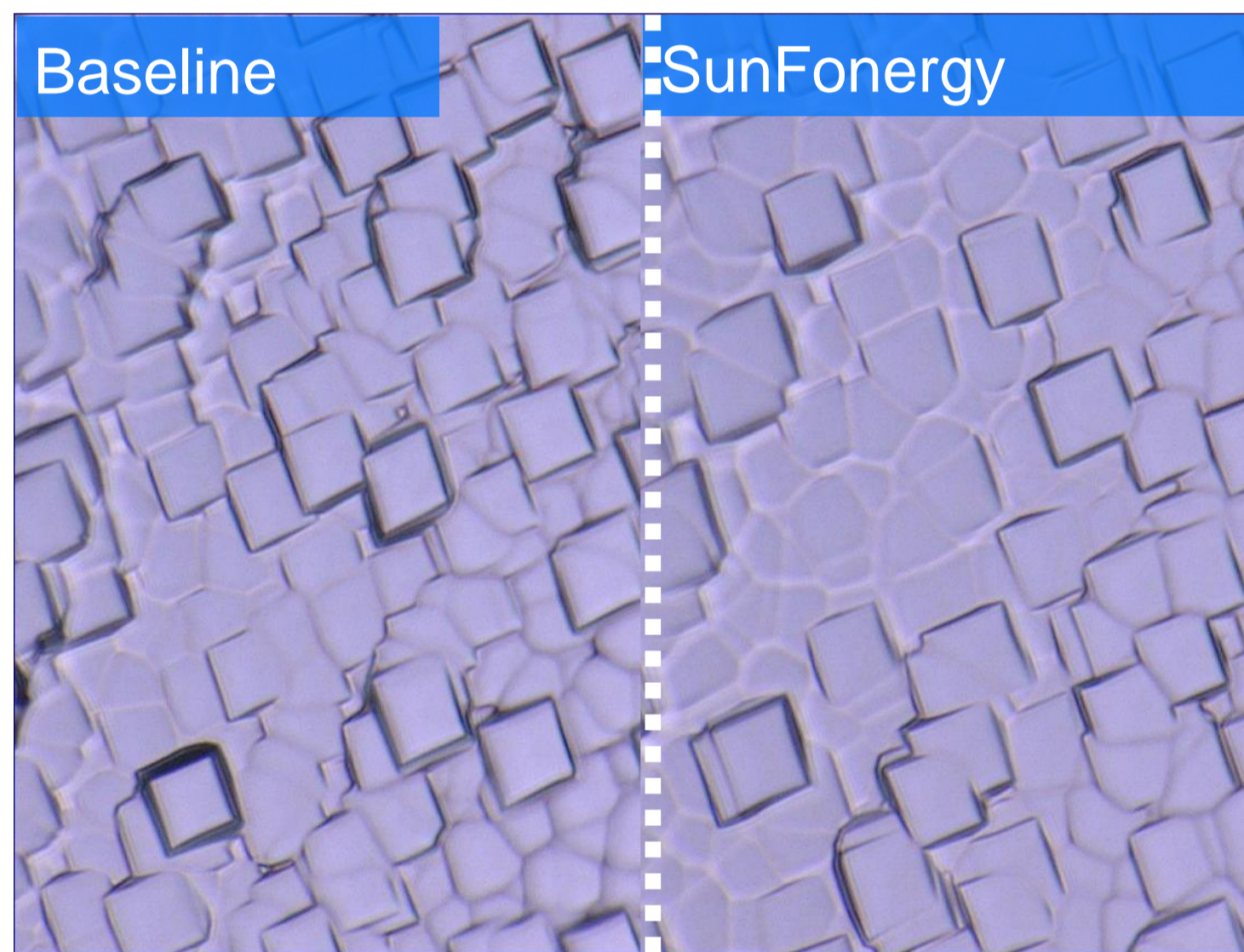
Alkaline Polishing Additive

BPL

High Adaptability & Higher Efficiency
 Suitable for both TOPCon and PERC processes, with superior backside protection and higher efficiency

Item	Eta	Uoc	Isc	FF	IRev2	Rs	Rsh
Baseline	24.910	0.7172	13.6464	84.014	0.0254	0.000269	4792
SunFonergy	24.941	0.7168	13.6264	84.299	0.0298	0.000162	4414
Baseline	23.405	0.6916	13.587	82.224	0.112	0.0012	443
SunFonergy	23.433	0.6919	13.598	82.218	0.104	0.0012	462

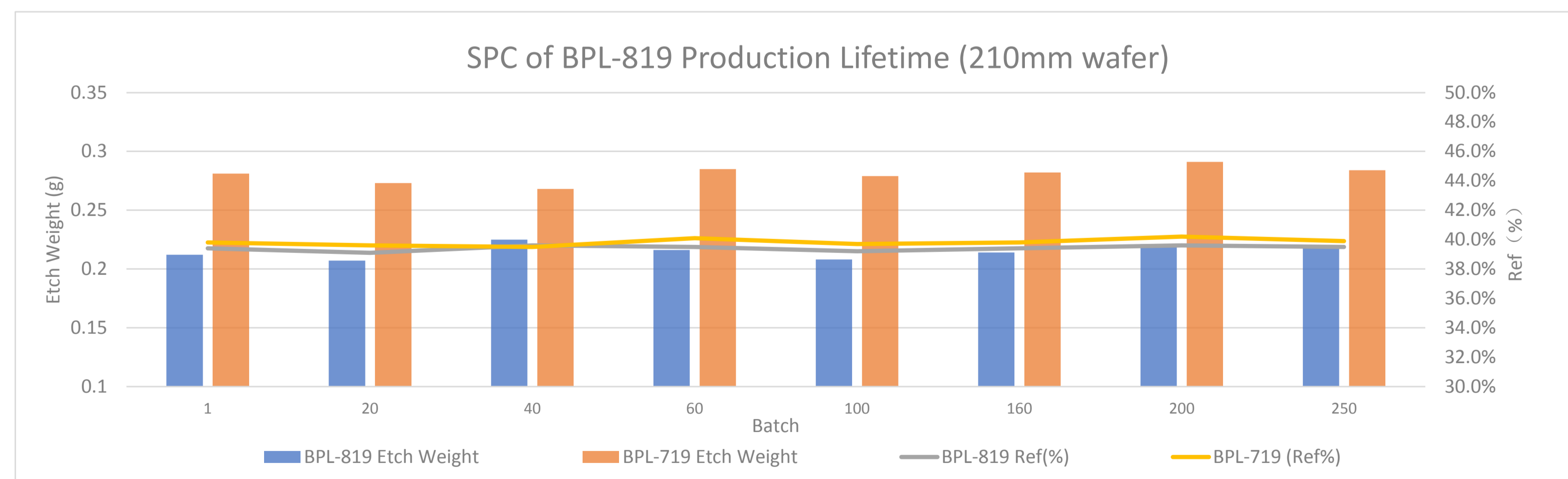
Better Morphology
 More uniform surface, smoother overlays among pyramid bases



Good Stability
 Little variance throughout production lifetime



Large Window of Optimization
 Suitable for a range of different etch weights and pyramid base sizes



High Adaptability & Higher Efficiency:
 Suitable for different processes with higher efficiency



Better Morphology:
 Smoother overlays among polished pyramid bases



Good Stability:
 Stable performance throughout production lifetime